MINILAB

Vapour Phase Reflow Furnace for Laboratory and Small-Series Production





+ TECHNICAL

+ FINANCIAL

+ ECO-FRIENDLY

Optimal soldering quality.

The most cost-effective solution on the market.

Environmentally friendly.



The **MiniLab model** is characterised by its compact design. Its small footprint (benchtop equipment) allows for easy and quick operation. The machine is therefore ideal for small-scale production while delivering **high soldering quality**. This model is intended for laboratories, design offices, and **manufacturers** of prototypes and small batches. Components such as QFPs, BGAs, Flip-Chips, and hybrids are soldered flawlessly with optimal quality.



General

- · Compact benchtop equipment
- Top loading
- Suitable for QFPs, BGAs, LGAs, PoPs, etc.
- · Soldering without oxygen or added N2 gas
- · No overheating of assemblies
- No temperature differential between components of different masses



Options

- · Adapter for double-sided PCB reflow
- · ReSy: repair tooling for QFPs and BGAs
- TE option for external connection of a temperature profile recorder
- · PC software for profile recording
- · Stainless steel grid for loading basket
- · Self-contained cooling unit



Features

- User-friendly touchscreen control
- Automated reflow process
- Automatic soldering
- Energy management system
- Controlled fluid level
- · Viewing window for process chamber



Technical Specifications

- Maintenance-free transport system (patented)
- Quick opening/closing system for the chamber during loading and unloading (patented)
- Memory for up to 16 programmes
- Easy temperature profile recording option

Technical data*	Overall length	Width	Height	Weight	Maximum board size	Heat transfer fluid capacity	Water connection	Maximum heating power	Power consumption	Electrical supply	Main fuse
Minilab	715 mm	625 mm	580 mm	70 kg	304 x 274 x 80 mm	3 kg	½" / 2,5-5 bar / 1I/min	1,8 kW	0,8 kW/h	230 VAC, 50/60 Hz, 2 kW	16 A, Typ "gL" ou "C"

^{*}subject to technical modifications

